



Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model

[List multiple models if applicable.]

HP A-MSR30-40 Router (JF229A)

HP A-MSR30-40 DC Router (JF287A)

HP A-MSR30-40 PoE Router (JF803A)

HP A-MSR30-60 Router (JF230A)

HP A-MSR30-60 DC Router (JF801A)

HP A-MSR30-60 PoE Router (JF804A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

| Item Description | Notes | Quantity of items included in product |
|--|---|---------------------------------------|
| Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) | With a surface greater than 10 sq cm | 4 |
| Batteries | All types including standard alkaline and lithium coin or button style batteries | 0 |
| Mercury-containing components | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries | 0 |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm | Includes background illuminated displays with gas discharge lamps | 0 |
| Cathode Ray Tubes (CRT) | | 0 |
| Capacitors / condensers (Containing PCB/PCT) | | 0 |
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height | | 0 |
| External electrical cables and cords | | 2 |
| Gas Discharge Lamps | | 0 |
| Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above) | | 4 |
| Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0 |

| | |
|--|---|
| Components and waste containing asbestos | 0 |
| Components, parts and materials containing refractory ceramic fibers | 0 |
| Components, parts and materials containing radioactive substances | 0 |

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

| Tool Description | Tool Size (if applicable) |
|------------------|---------------------------|
| Screw driver | 2# |
| | |
| | |
| | |
| | |

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 1, and then remove mounting angle 1.
2. Unscrew the screws on card 2, and then remove card 2.
3. Unscrew the screws on card 3, and then remove card 3.
4. Unscrew the screws on filler panel 4, and then remove filler panel 4.
5. Unscrew the screws on filler panel 6, and then remove filler panel 6.
6. Unscrew the screws on guide rail 5, and then remove guide rail 5.
7. Unscrew the screws on guide rail 7, and then remove guide rail 7.
8. Unscrew the screws on guide rail 8, and then remove guide rail 8.
9. Unscrew the screws on card 9, and then remove card 9.
10. Unscrew the screws on cover 10, and then remove cover 10.
11. Unscrew the screws on power supply 11, and then remove power supply 11.
12. Remove all of the inner cables.
13. Unscrew the screws on bracket 12 and remove bracket 12.
14. Unscrew the screws on card 13, and then remove card 13.
15. Unscrew the screws on PCB 14, and then remove PCB 14.
16. Unscrew the screws on PCB 15, and then remove PCB 15.
17. Unscrew the screws on fan 16, and then remove fan 16.
18. Remove all of the labels.
19. Unscrew the screws and then remove wiring channel 1-2.
20. Unscrew the screws on PCB 2-1, and then remove PCB 2-1.
21. Remove Insulating pad 2-3 from front panel 2-2.
22. Remove all of the shielding finger 2-4.
23. Unscrew the screws on PCB 3-5, and then remove pulled handle 3-1、 washer3-3、 PCB 3-4.
24. Remove all of the shielding finger 3-4.
25. Remove shielding finger 4-2 from filler panel 4-1.
26. Remove shielding finger 5-2.
27. Remove shielding finger 6-2 from filler panel 6-1.
28. Remove shielding finger 7-2.
29. Remove shielding finger 8-2.
30. Unscrew the screws on PCB 9-3, and then remove PCB 9-3.
31. Remove all of the shielding finger 9-2.
32. Remove plastic panel 10-2 from cover 10-1.
33. Remove film 10-3 from plastic panel 10-2.
34. Unscrew the screws on power supply 11-3, and then remove power supply 11-3.

35. Remove all of the conductive foam 11-1.
36. Remove PCB 13-1.
37. Remove PCB 13-5.
38. Unscrew the screws on PCB 13-2, and then remove PCB 13-2.
39. Unscrew the screws on PCB 13-6, and then remove PCB 13-6.
40. Unscrew the screws on PCB 13-8, and then remove PCB 13-8.
41. Remove all of the conductive foam 13-4.
42. Remove all of the shielding finger 13-3.
43. Remove all of the conductive foam 17-2.
44. Remove all of the shielding finger 17-3.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

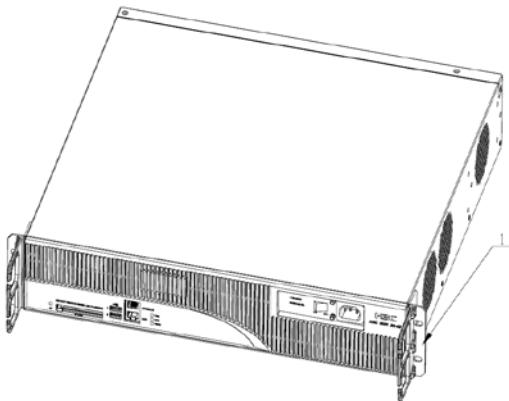


Figure 1 Remove mounting angle

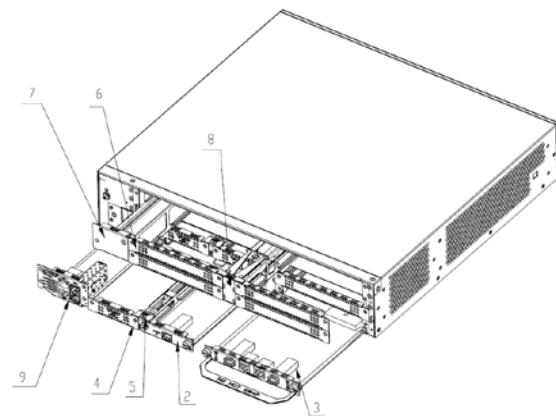


Figure 2 Rear of the product

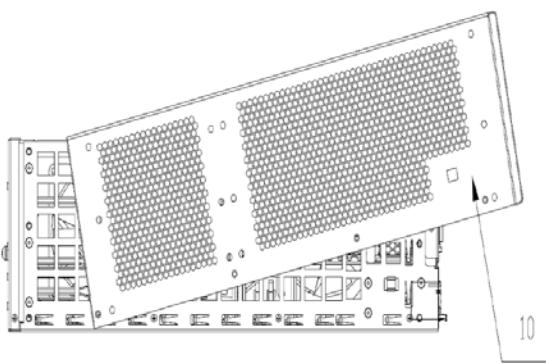


Figure 3 Treatments to cover

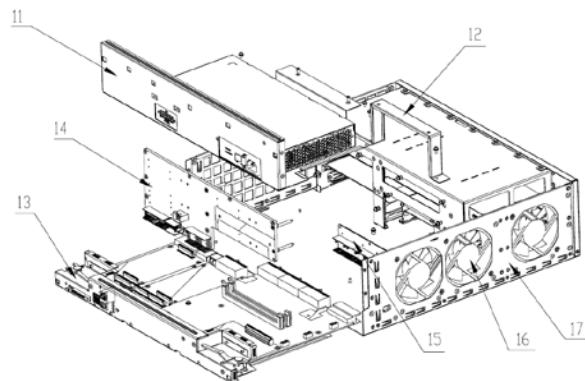


Figure 4 Treatments to the product

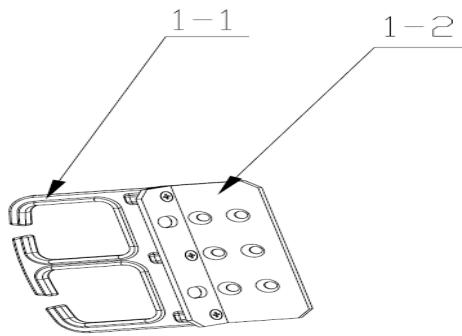


Figure 5 Treatments to mount angle

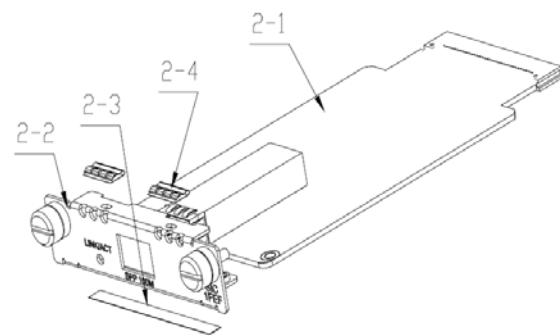


Figure 6 Treatments to the card 2

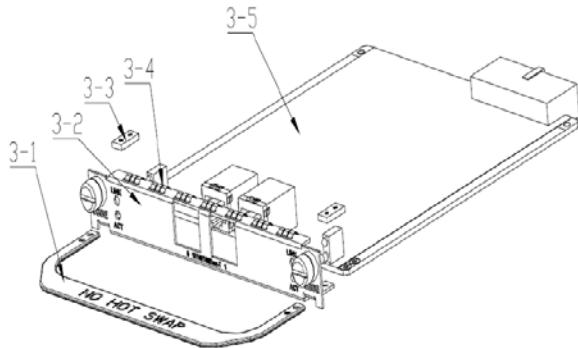


Figure 7 Treatments to the card 3

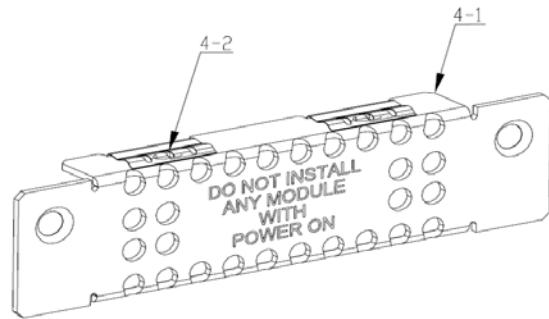


Figure 8 Treatments to filler panel 4

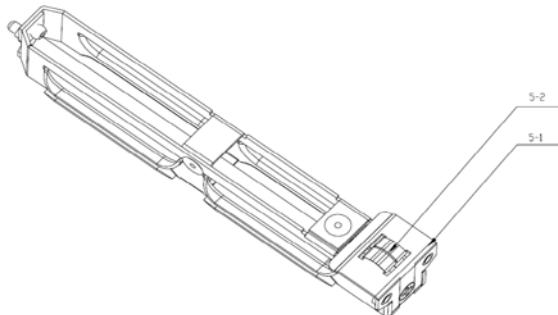


Figure 9 Treatments to guide rail 5.

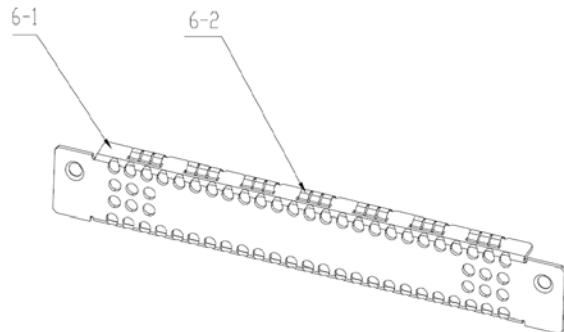


Figure 10 Treatments to filler panel 6

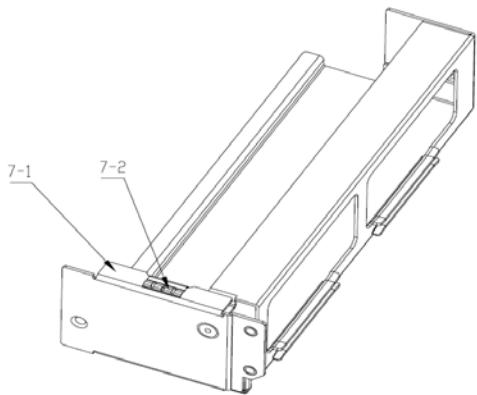


Figure 11 Treatments to guide rail 7

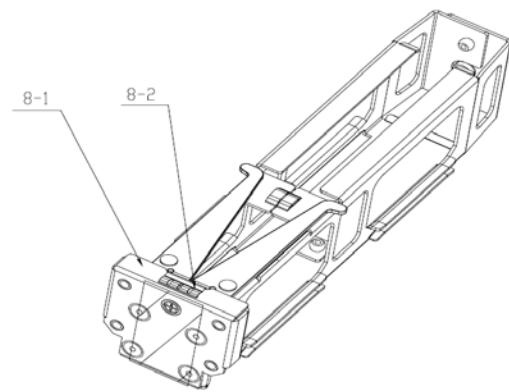


Figure 12 Treatments to guide rail 8

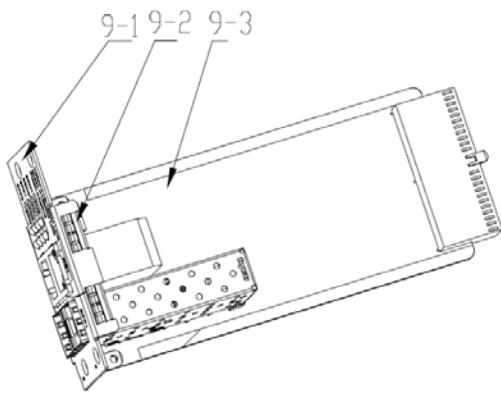


Figure 13 Treatments to card 9

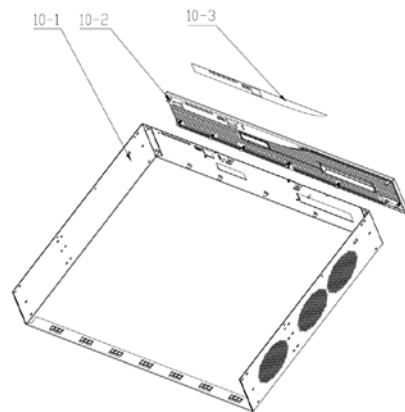


Figure 14 Treatments to cover 10

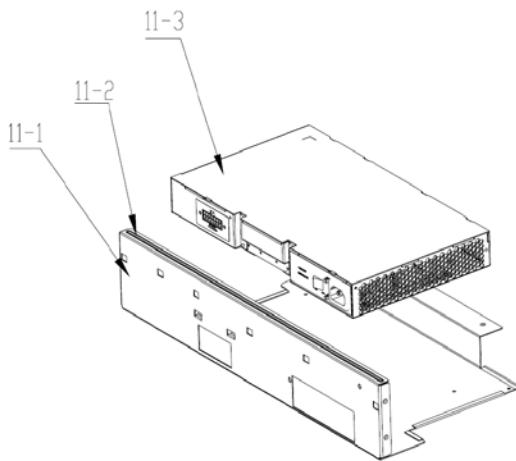


Figure 15 Treatments to power supply 11

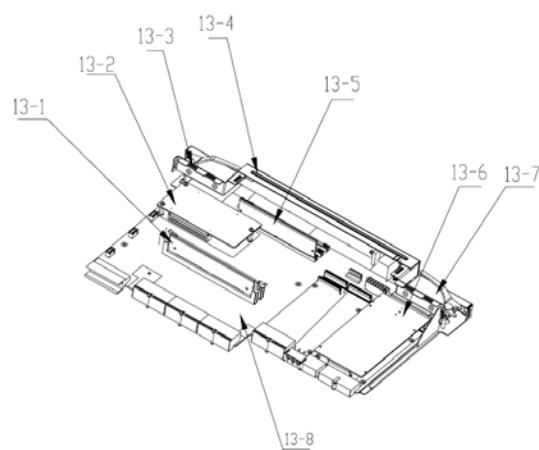


Figure 16 Treatments to card13

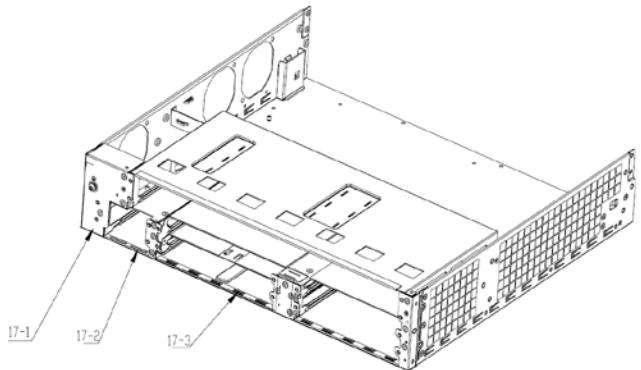


Figure 17 Treatments to base 17